

# SN54ABTR2245, SN74ABTR2245 OCTAL TRANSCEIVERS AND LINE/MEMORY DRIVERS WITH 3-STATE OUTPUTS

SCBS680A – MARCH 1997 – REVISED MAY 1997

- Outputs Have Equivalent 25- $\Omega$  Series Resistors, So No External Resistors Are Required
- State-of-the-Art *EPIC-II B*<sup>™</sup> BiCMOS Design Significantly Reduces Power Dissipation
- High-Impedance State During Power Up and Power Down
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Typical  $V_{OLP}$  (Output Ground Bounce) < 1 V at  $V_{CC} = 5$  V,  $T_A = 25^\circ\text{C}$
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and Thin Very Small-Outline (DGV) Packages, Ceramic Chip Carriers (FK), and Plastic (N) and Ceramic (J) DIPs

## description

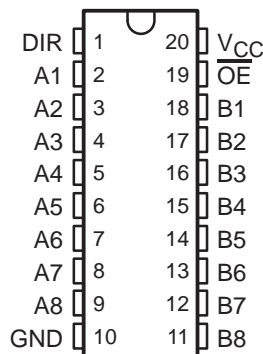
These octal transceivers and line drivers are designed for asynchronous communication between data buses. The devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ( $\overline{OE}$ ) input can be used to disable the device so the buses are effectively isolated.

Both the A-port and B-port outputs, which are designed to sink up to 12 mA, include equivalent 25- $\Omega$  series resistors to reduce overshoot and undershoot.

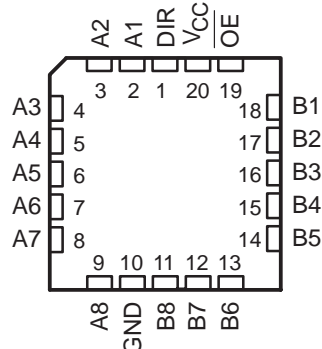
When  $V_{CC}$  is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABTR2245 is characterized for operation over the full military temperature range of  $-55^\circ\text{C}$  to  $125^\circ\text{C}$ . The SN74ABTR2245 is characterized for operation from  $-40^\circ\text{C}$  to  $85^\circ\text{C}$ .

SN54ABTR2245 . . . J PACKAGE  
SN74ABTR2245 . . . DB, DGV, DW, N, OR PW PACKAGE  
(TOP VIEW)



SN54ABTR2245 . . . FK PACKAGE  
(TOP VIEW)



FUNCTION TABLE

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation



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**TEXAS  
INSTRUMENTS**

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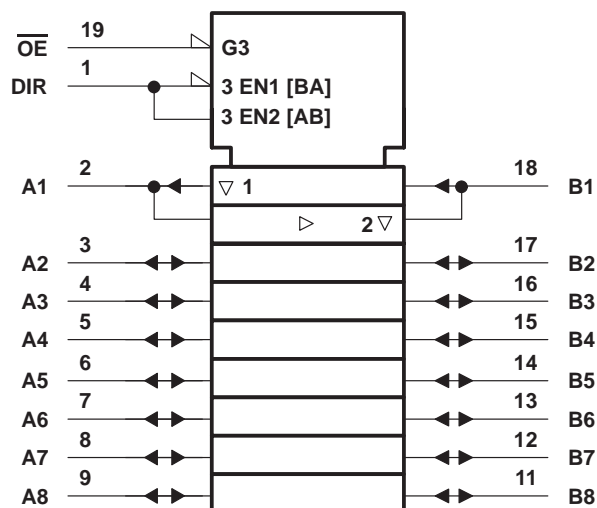
# SN54ABTR2245, SN74ABTR2245

## OCTAL TRANSCEIVERS AND LINE/MEMORY DRIVERS

### WITH 3-STATE OUTPUTS

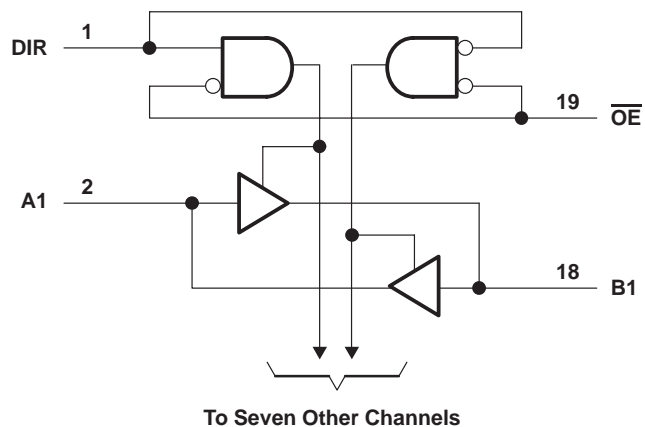
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#### logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

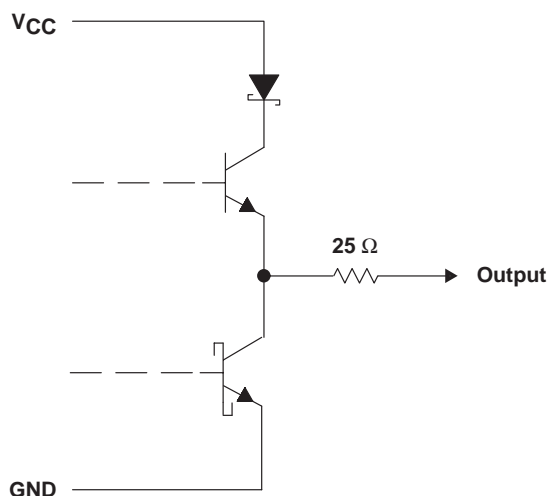
#### logic diagram (positive logic)



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## output schematic



All resistor values shown are nominal.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$	–0.5 V to 7 V
Input voltage range, $V_I$ (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, $V_O$	–0.5 V to 5.5 V
Current into any output in the low state, $I_O$	30 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	–18 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ )	–50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	
DB package	115°C/W
DGV package	146°C/W
DW package	97°C/W
N package	67°C/W
PW package	128°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

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## OCTAL TRANSCEIVERS AND LINE/MEMORY DRIVERS

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#### recommended operating conditions (see Note 3)

		SN54ABTR2245		SN74ABTR2245		UNIT
		MIN	MAX	MIN	MAX	
$V_{CC}$	Supply voltage	4.5	5.5	4.5	5.5	V
$V_{IH}$	High-level input voltage	2		2		V
$V_{IL}$	Low-level input voltage		0.8		0.8	V
$V_I$	Input voltage	0	$V_{CC}$	0	$V_{CC}$	V
$I_{OH}$	High-level output current		–12		–12	mA
$I_{OL}$	Low-level output current		12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5	5	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		$\mu s/V$
$T_A$	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

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## OCTAL TRANSCEIVERS AND LINE/MEMORY DRIVERS

### WITH 3-STATE OUTPUTS

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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER		TEST CONDITIONS	T <sub>A</sub> = 25°C			SN54ABTR2245		SN74ABTR2245		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V <sub>IK</sub>		V <sub>CC</sub> = 4.5 V, I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V
V <sub>OH</sub>		V <sub>CC</sub> = 4.5 V, I <sub>OH</sub> = -1 mA	3.35			3.3		3.35		V
		V <sub>CC</sub> = 5 V, I <sub>OH</sub> = -1 mA	3.85			3.8		3.85		
		V <sub>CC</sub> = 4.5 V, I <sub>OH</sub> = -3 mA				3		3.1		
		V <sub>CC</sub> = 4.5 V, I <sub>OH</sub> = -12 mA	2.6					2.6		
V <sub>OL</sub>		V <sub>CC</sub> = 4.5 V, I <sub>OL</sub> = 8 mA			0.65		0.8		0.65	V
		V <sub>CC</sub> = 4.5 V, I <sub>OL</sub> = 12 mA			0.8				0.8	
V <sub>hys</sub>				100						mV
I <sub>I</sub>	Control inputs	V <sub>CC</sub> = 0 to 5.5 V, V <sub>I</sub> = V <sub>CC</sub> or GND			±1		±1		±1	μA
	A or B ports	V <sub>CC</sub> = 2.1 V to 5.5 V, V <sub>I</sub> = V <sub>CC</sub> or GND			±20		±20		±20	
I <sub>OZH</sub> ‡		V <sub>CC</sub> = 2.1 V to 5.5 V, V <sub>O</sub> = 2.7 V, OE ≥ 2 V			10		10		10	μA
I <sub>OZL</sub> ‡		V <sub>CC</sub> = 2.1 V to 5.5 V, V <sub>O</sub> = 0.5 V, OE ≥ 2 V			-10		-10		-10	μA
I <sub>OZPU</sub> §		V <sub>CC</sub> = 0 to 2.1 V, V <sub>O</sub> = 0.5 V to 2.7 V, OE = X			±50		±50		±50	μA
I <sub>OZPD</sub> §		V <sub>CC</sub> = 2.1 V to 0, V <sub>O</sub> = 0.5 V to 2.7 V, OE = X			±50		±50		±50	μA
I <sub>off</sub>		V <sub>CC</sub> = 0, V <sub>I</sub> or V <sub>O</sub> ≤ 4.5 V			±100				±100	μA
I <sub>CEX</sub>		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V, Outputs high			50		50		50	μA
I <sub>O</sub> ¶		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 2.5 V	-25		-100	-25	-100	-25	-100	mA
I <sub>CC</sub>	A or B ports	V <sub>CC</sub> = 5.5 V, I <sub>O</sub> = 0, V <sub>I</sub> = V <sub>CC</sub> or GND, Outputs high		1	250		250		250	μA
		Outputs low		24	32		32		32	mA
		Outputs disabled		0.5	250		250		250	μA
ΔI <sub>CC</sub> #	Data inputs	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND, Outputs enabled			1.5		1.5		1.5	mA
		Outputs disabled			0.05		0.05		0.05	
	Control inputs	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND			1.5		1.5		1.5	
C <sub>i</sub>		V <sub>I</sub> = 2.5 V or 0.5 V			3					pF
C <sub>io</sub>		V <sub>O</sub> = 2.5 V or 0.5 V			6					pF

\* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at V<sub>CC</sub> = 5 V.

‡ The parameters I<sub>OZH</sub> and I<sub>OZL</sub> include the input leakage current.

§ This parameter is characterized but not production tested.

¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L = 50$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$			SN54ABTR2245		SN74ABTR2245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	A or B	B or A	1	2.5	3.4	1	4	1	3.8	ns
$t_{PHL}$			1	3.2	4.2	1	4.6	1	4.5	
$t_{PZH}$	$\overline{OE}$	A or B	1.5	3.6	4.9	1.5	6.3	1.5	6.1	ns
$t_{PZL}$			1.5	3.9	5.3	1.5	6.6	1.5	6.3	
$t_{PHZ}$	$\overline{OE}$	A or B	1.5	3.6	4.7	1.5	5.5	1.5	5.3	ns
$t_{PLZ}$			1.5	3.3	4.4	1.5	4.9	1.5	4.8	

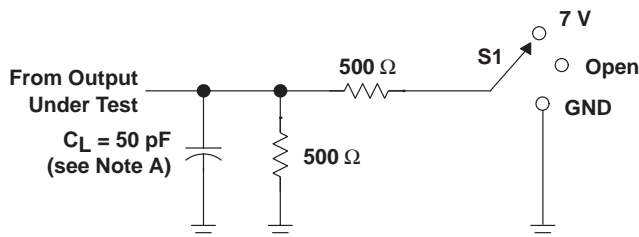
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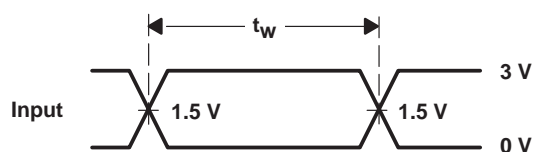
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## PARAMETER MEASUREMENT INFORMATION

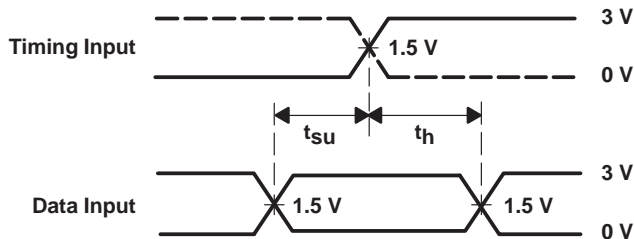


LOAD CIRCUIT

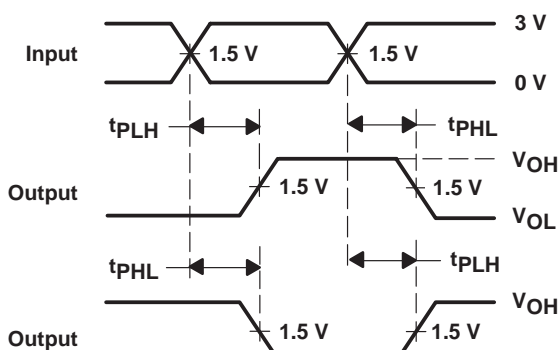
TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	7 V
$t_{PHZ}/t_{PZH}$	Open



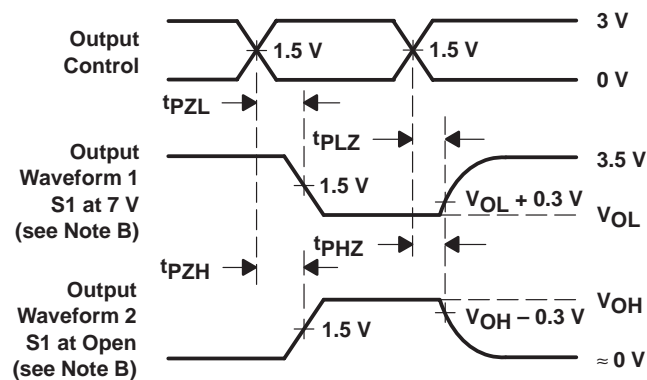
VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .
  - D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABTR2245DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ABTR2245PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1



## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABTR2245DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ABTR2245PWR	TSSOP	PW	20	2000	367.0	367.0	38.0

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